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### (54) HEAT SINK STRUCTURE FOR AUDIO **EQUIPMENT**

(71) Applicant: **DENSO TEN Limited**, Kobe-shi (JP)

Inventor: Noboru HIDAKA, Kobe-shi (JP)

Assignee: **DENSO TEN Limited**, Kobe-shi (JP)

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#### (57)ABSTRACT

A heat sink structure that is used for audio equipment includes a base and a plurality of heat dissipation fins. The heat dissipation fins extend from a predetermined surface of the base in a first direction orthogonal to the predetermined surface. The heat dissipation fins are arranged side by side in a second direction orthogonal to the first direction. In a cross-section in a plane parallel to the first and second directions, (i) each of the heat dissipation fins has a first side surface and a second side surface, the first and second surfaces facing oppositely from each other in the second direction, and (ii) inclinations, relative to the predetermined surface, of the first and second side surfaces of adjacent ones of the heat dissipation fins are different from each other.

